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ABSTRACT

A method for dicing a semiconductor wafer wherein a semiconductor wafer (W) with circuits in many regions sectioned by crosswise streets is diced into individual semiconductor chips each having a circuit. The circuit face of the semiconductor wafer (W) is covered with a tape member (10), and a part of the tape member (10) covering the top of the streets is removed by cutting to form a cut groove (11). The semiconductor wafer (W) clear of the part of the tape member (10) covering the top of the crosswise streets is chemically etched to erode the crosswise streets and thus diced into individual semiconductor chips. This economical method enables formation of high quality chips free of cracks or stresses.

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